



Vantage Technology Qualifies SlurryScope™ System at Major IC Production Fabs
Patented laser particle-sensing techniques, powerful algorithms and multicore image processing merge in innovative metrology tool that continuously analyzes undiluted slurry in real time

***Mega Fluid Systems embeds Vantage SlurryScope tool in
Next Generation Slurry Delivery System***

CAMPBELL, CA – July 5, 2012 – Vantage Technology today announced it has formally qualified its SlurryScope™ System at major IC production fabs, underscoring its capabilities to continuously analyze undiluted slurry in real time. Used during the chemical-mechanical planarization (CMP) of semiconductor wafers, the innovative metrology tool orchestrates patented laser particle-sensing techniques, powerful algorithms and multicore image processing to analyze production strength slurry with real-time measurements. The SlurryScope System instantly detects and profiles oversized particles in the 1.0 -to-12.0+ micron range that can cause damaging micro-scratches to wafers.

According to Vantage CEO Paul Magliocco, the SlurryScope System commenced field testing at major wafer fab facilities in late 2010. “The positive feedback that we have garnered has affirmed the increasing need for the unique capabilities that our product delivers. We believe our SlurryScope System is the first particle sensor capable of analyzing and quantifying undiluted production strength slurry continuously and in real time as it is delivered to the CMP stage.”

Mega Fluid Systems Embeds SlurryScope Capabilities

In a related announcement, Jack McCann, president of [Mega Fluid Systems](http://www.megafluidsystems.com), today confirmed that his company’s newest Slurry Delivery System (SDS) has embedded Vantage’s metrology tool. “We are currently experiencing strong interest in our SDS-SlurryScope combination, and are pleased to announce that we have just shipped one of the first of these next generation systems to a major IC production Fab.” Based in Tualatin, Oregon, Mega Fluid Systems is a leading supplier of world class chemical and slurry delivery equipment. For more information visit www.megafluidsystems.com or phone 971-277-7000.

According to Magliocco, the Mega Fluid announcement highlights the versatility of the SlurryScope System to be installed at various points in the line to manage undiluted slurry delivery. “We anticipate that our SlurryScope System will be increasingly integrated into the CMP processing steps as the real-time data it provides is used to optimize slurry and filter life cycles, while eliminating the waste associated with the conventional practice of diluting slurries before analyzing their particulate compositions.”

Semicon West 2012 Exhibits

Vantage will be demonstrating its innovative metrology tool from two booths at Semicon West, which opens its three-day run in San Francisco (Moscone Center) on July 10th. Attendees can view Vantage’s SlurryScope System at the [Malema Sensors booth # 625](#) or at the [Levitronix booth # 1440](#). Vantage executives will be on hand at both booths to interact with attendees. Headquartered in Florida, Malema Sensors will be exhibiting closed-loop flow control modules

that precisely control slurry delivery to the polishing platen at the CMP system. Zurich-based Levitronix will be showcasing its line of bearingless pumps with a low shear force design for conveying slurries to CMP processing without adding agglomeration.

About Vantage Technology Corporation

Operating from headquarters in Campbell, California, Vantage Technology Corporation was founded in 2010 by a cadre of Silicon Valley veterans with extensive semiconductor test experience. Focused on developing real-time micro-analytical metrology tools using advanced laser technology, proprietary algorithms and multicore image processing techniques, the company has targeted its first product at the semiconductor industry. Called the SlurryScope™ System, this initial real-time tool continuously detects large particle counts in undiluted slurry. Early detection of oversized slurry particles enables timely corrective action that can minimize defects and wafer micro-scratches caused by particulate agglomeration at the chemical-mechanical planarization (CMP) stage. For more information, visit www.VantageTechCorp.com.

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SlurryScope™ System elevates particulate analysis of slurries to new heights as it analyzes and quantifies undiluted production strength slurry continuously in real time. Armed with early-warning data quantifying oversized particle distributions, semiconductor manufacturers can take action to prevent yield-diminishing micro-scratches and damaging agglomeration during the chemical-mechanical-planarization and polishing (CMP) of wafers.

(Vantage Technology Corporation, Campbell, CA)